

01/03/02
JC893 U.S. PTO

01-07-98

ATTY.DOCKET NO. AMAT/5699/CMP/CMP/RKK

A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Box Patent Application
Commissioner of Patents and Trademarks
Washington, D.C. 20231

Re: Inventor(s): Liang-Yuh Chen, Wei-Yung Hsu, Alain Duboust, Ratson Morad, Daniel A. Carl, Sasson Somekh, and Dan Maydan
Title: Planarization of Substrates Using Electrochemical Mechanical Polishing

Transmitted herewith is the patent application identified above, including:

Specification, claims and abstract, totaling 49 pages.
 Drawings totaling 19 pages, Formal Informal.
 Unexecuted Declaration and Power of Attorney.
 Information Disclosure Statement w/ Form 1449 and References.
 Assignment of the invention to **Applied Materials, Inc.**
 Assignment Recordation Cover Sheet

J1011 U.S. PTO
01/03/02
J1010/038066

FEE CALCULATION

	NUMBER OF CLAIMS FILED	LESS NUMBER PAID BY BASIC FEE	NUMBER OF EXTRA CLAIMS (Not less than zero)	LARGE ENTITY FEE
Basic Fee				\$740.00
Total Claims	39	- 20 = 19	X \$18 =	\$342.00
Independent Claims	4	- 3 = 1	X \$84 =	\$84.00
First Presentation of Multiple Dependent Claims +250				-0-
Total Filing Fee Calculation				\$1,166.00

The Commissioner is hereby authorized to charge _____ to Deposit Account No. _____

The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. _____. A duplicate copy of this transmittal is enclosed.

Please address all future correspondence to:

PATENT COUNSEL
APPLIED MATERIALS, INC.
Legal Affairs Department
P.O.BOX 450A
Santa Clara, CA. 95052

I hereby certify that this correspondence is being deposited with the United States Postal Service as express mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231.

Express Mail Receipt No. EV041916468US
Date of Deposit 01/03/02
Signature B. Todd Patterson

Respectfully submitted,

B. Todd Patterson

B. Todd Patterson
Registration No. 37,906